RELIABILITY REPORT

FOR

MAX6100EUR+

PLASTIC ENCAPSULATED DEVICES

October 24, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX6100EUR+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim''s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim''s quality and reliability standards.

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I. Device Description

A. General

The MAX6100-MAX6107 are low-cost, low-dropout (LDO), micropower voltage references. These three-terminal references are available with output voltage options of 1.25V, 1.8V, 2.048V, 2.5V, 3V, 4.096V, 4.5V and 5V. They feature a proprietary curvature-correction circuit and laser-trimmed, thin-film resistors that result in a low temperature coefficient of 75ppm/°C (max) and an initial accuracy of ±0.4% (max). These devices are specified over the extended temperature range (-40°C to +85°C). These series-mode voltage references draw only 90µA of supply current and can source 5mA and sink 2mA of load current. Unlike conventional shunt-mode (two-terminal) references that waste supply current and require an external resistor, these devices offer a supply current that is virtually independent of the supply voltage (with only a 4µA/V variation with supply voltage) and do not require an external resistor. Additionally, these internally compensated devices do not require an external compensation capacitor and are stable with load capacitance. Eliminating the external compensation capacitor saves valuable board area in space-critical applications. Low dropout voltage and supply-independent, ultra-low supply current make these devices ideal for battery-operated, high-performance, low-voltage systems. The MAX6100-MAX6107 are available in tiny 3-pin SOT23 packages.

II. Manufacturing Information

A. Description/Function:	Low-Cost, Micropower, Low-Dropout, High-Output-Current, SOT23 Voltage References
B. Process:	B12
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon, California or Texas
E. Assembly Location:	Carsem, Malaysia; ISPL, Philippines; Unisem, Malaysia; UTL, Thailand
F. Date of Initial Production:	April 13, 2001

III. Packaging Information

A. Package Type:	3-pin SOT23
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	84-1lmisr4 Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-0901-0179
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	250*°C/W
K. Single Layer Theta Jc:	130°C/W

IV. Die Information

A. Dimensions:	44 X 31 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	1.2 microns (as drawn)
F. Minimum Metal Spacing:	1.2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 160 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 6.71 \times 10^{-9}$

λ = 6.71 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the B8 Process results in a FIT Rate of 2.71 @ 25C and 17.30 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The RF24-7 die type has been found to have all pins able to withstand a HBM transient pulse of 1500 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of 250 mA.

Table 1

Reliability Evaluation Test Results

MAX6100EUR+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	160	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data